



# Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model

[List multiple models if applicable.]

HP Z24i 24-inch IPS Display

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

| Item Description   | Notes   | Quantity of items included in product |
|--|---|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)                                     | With a surface greater than 10 sq cm<br>USB BD, IF BD, POWER BD, FK BD                | 4                                     |
| Batteries  | All types including standard alkaline and lithium coin or button style batteries      | 0                                     |
| Mercury-containing components  | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0                                     |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm                                  | Includes background illuminated displays with gas discharge lamps Panel               | 1                                     |
| Cathode Ray Tubes (CRT)  |   | 0                                     |
| Capacitors / condensers (Containing PCB/PCT)   |   |                                       |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height             | Power BD only (C805)  | 1                                     |
| External electrical cables and cords   | USB cable, VGA cable, D-sub cable, Power cord   | 4                                     |
| Gas Discharge Lamps  |   | 0                                     |
| Plastics containing Brominated Flame Retardants  |   | 0                                     |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations.      | 0                                     |
| Components and waste containing asbestos   |   | 0                                     |
| Components, parts and materials containing refractory ceramic fibers                                 |   | 0                                     |
| Components, parts and materials containing radioactive substances                                    |   | 0                                     |

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description                           | Tool Size (if applicable) |
|--|---------------------------|
| Description #1 SCREW DRIVER(PHILLIPS HEAD) | #0                        |
| Description #2 SCREW DRIVER(PHILLIPS HEAD) | #1                        |
| Description #3 SCREW DRIVER(PHILLIPS HEAD) | #2                        |
| Description #4                             |                           |
| Description #5                             |                           |

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Stand Base From Display Head
2. Remove Rear Cover From Display Head
3. Remove Front Cover From Display Head
4. Remove Key Board Off From Front Cover
5. Disassemble Front Cover ASSY
6. Disassemble Rear Cover ASSY
7. Take Screw(\*4) Off From Chassis Cover & Remove Panel
8. Take Screw(x9) Off From P.C.B
9. Take Screw(x6) Off From P.C.B
10. Take Off P.C.B From Chassis& Remove BKT (Printed Circuit Assemblies>10cm\*\*2)
11. Remove Mylar From Chassis Cover
12. Remove Gasket From Chassis Cover
13. LCD PANEL EXPLODE
14. Remove VESA Cover&Pivot Cover off Stand Base
15. Remove Riser Lift Cover off Stand Base
16. Remove Base Cover & Base Cover BKT Off Stand Base
17. Remove Stand Front Cover off Stand BKT
18. Remove Stand Rear Cover Off Stand BKT
19. Remove Vesa Cover Assy Off Stand BKT
20. Remove Vesa Cover Off VESA BKT

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

# HP Z24i Disassembly Process

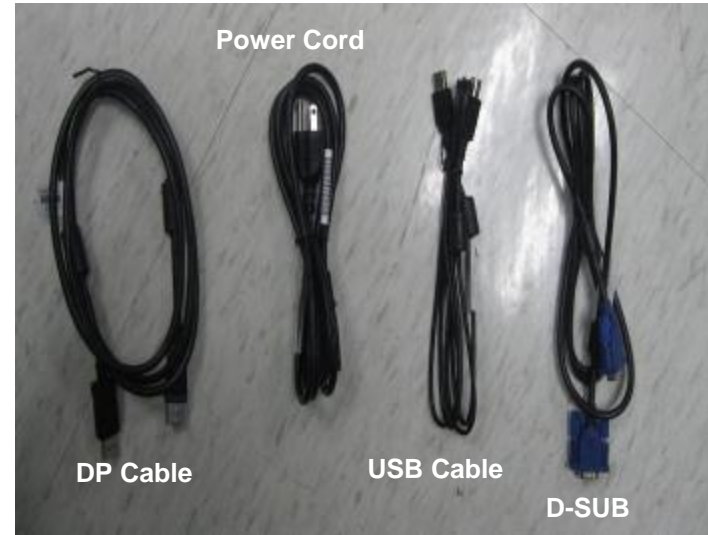
- Steve Chou
- Mechanical Engineer
- March-04-2013



# External Electric Cables Dissecting Process



1.Remove Cable From Display Head.



2.Dissecting To Complete.

# ▶ Remove Stand Base From Display Head



3. Pull the release button



4. Remove Stand Base From Display Head.



# Remove Rear Cover From Display Head



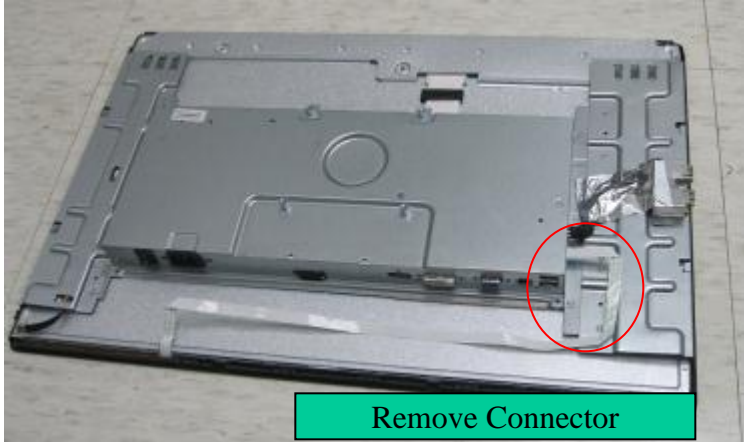
5.Remove four wall mount screws from display head .



6.Remove Rear Cover From Display Head.



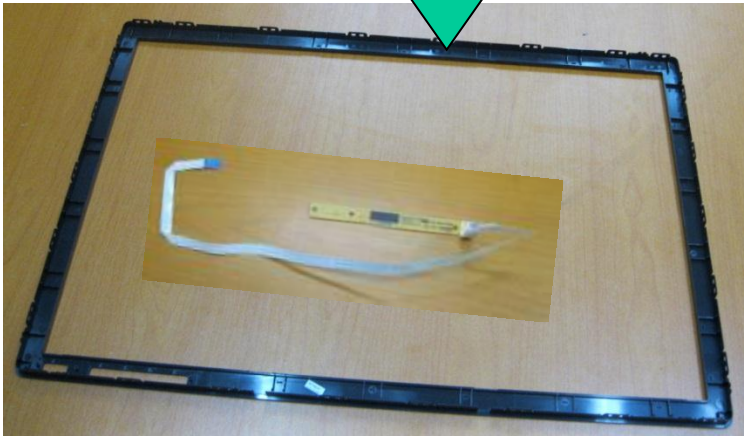
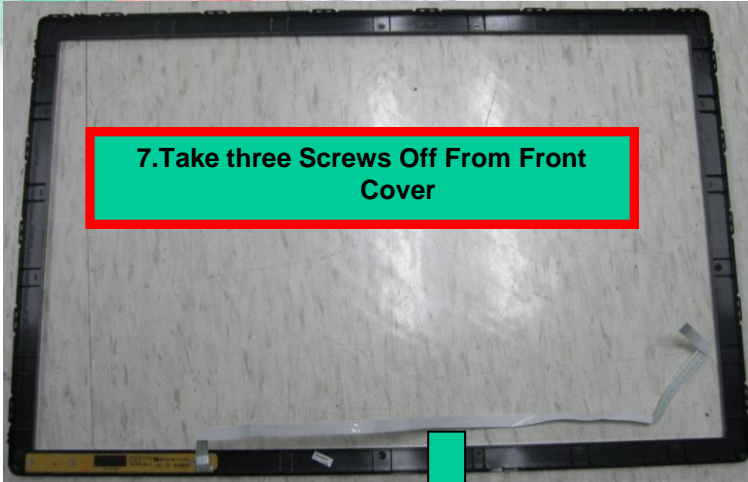
# Remove Front Cover From Display Head



7.Remove Front Cover.

# Remove Key Board Off From Front Cover

7. Take three screws off from front cover

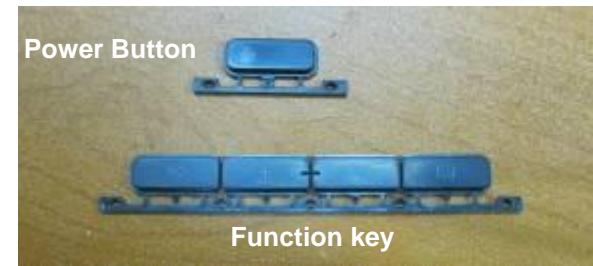
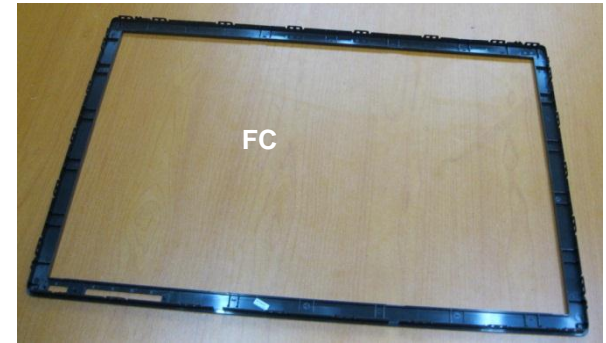


8. Remove key board from FC





# Disassemble Front Cover ASSY





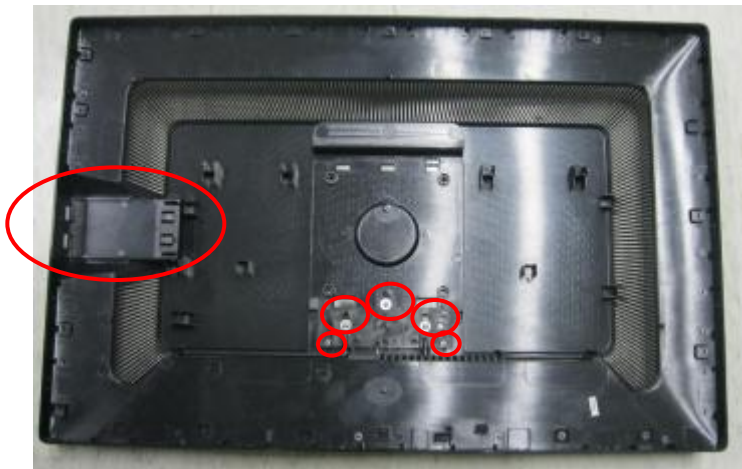
# Disassemble Rear Cover ASSY



Rear cover



Release button



Slider



Spring



Information card



8.Remove 5 screws



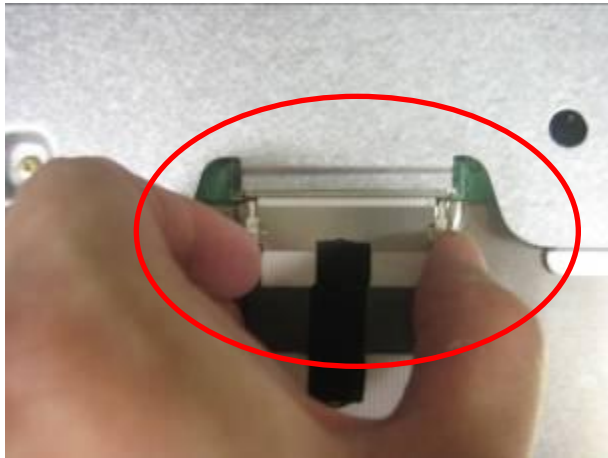
# Take Screw(\*4) Off From Chassis Cover & Remove Panel



1.Remove connector from panel.



2.Take Screw(x4) Off from Chassis cover



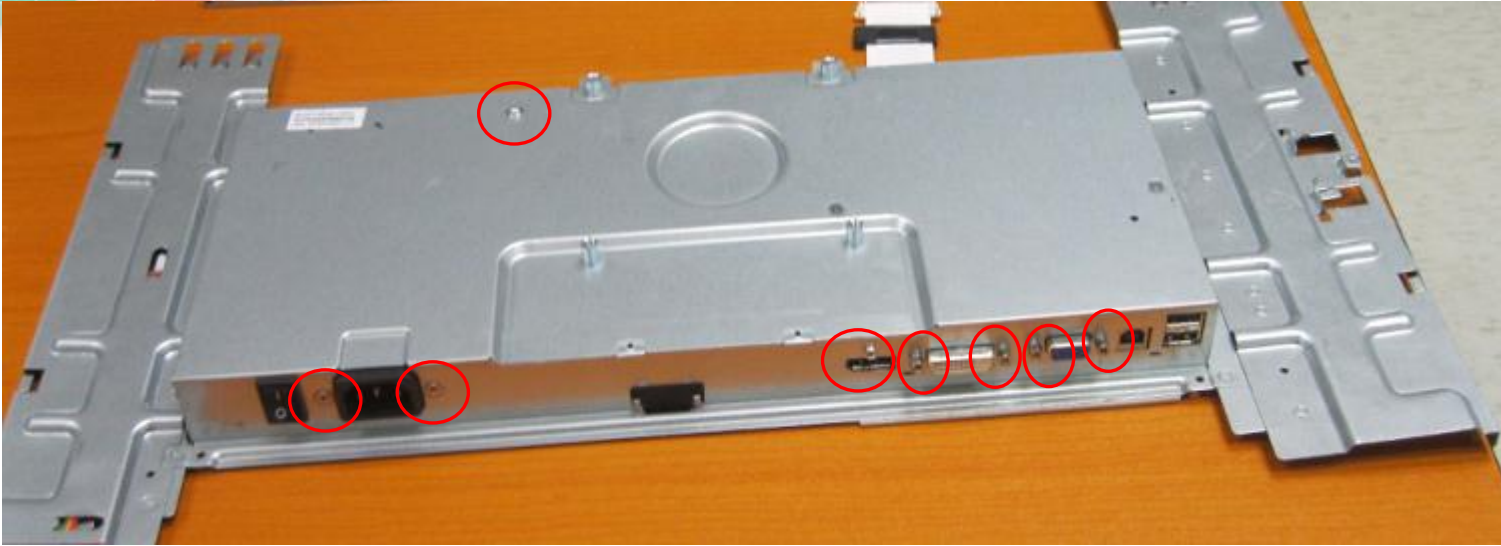
3.Remove connector off from Panel.



4.Remove the panel.



# ▶ Take Screw(x8) Off From P.C.B



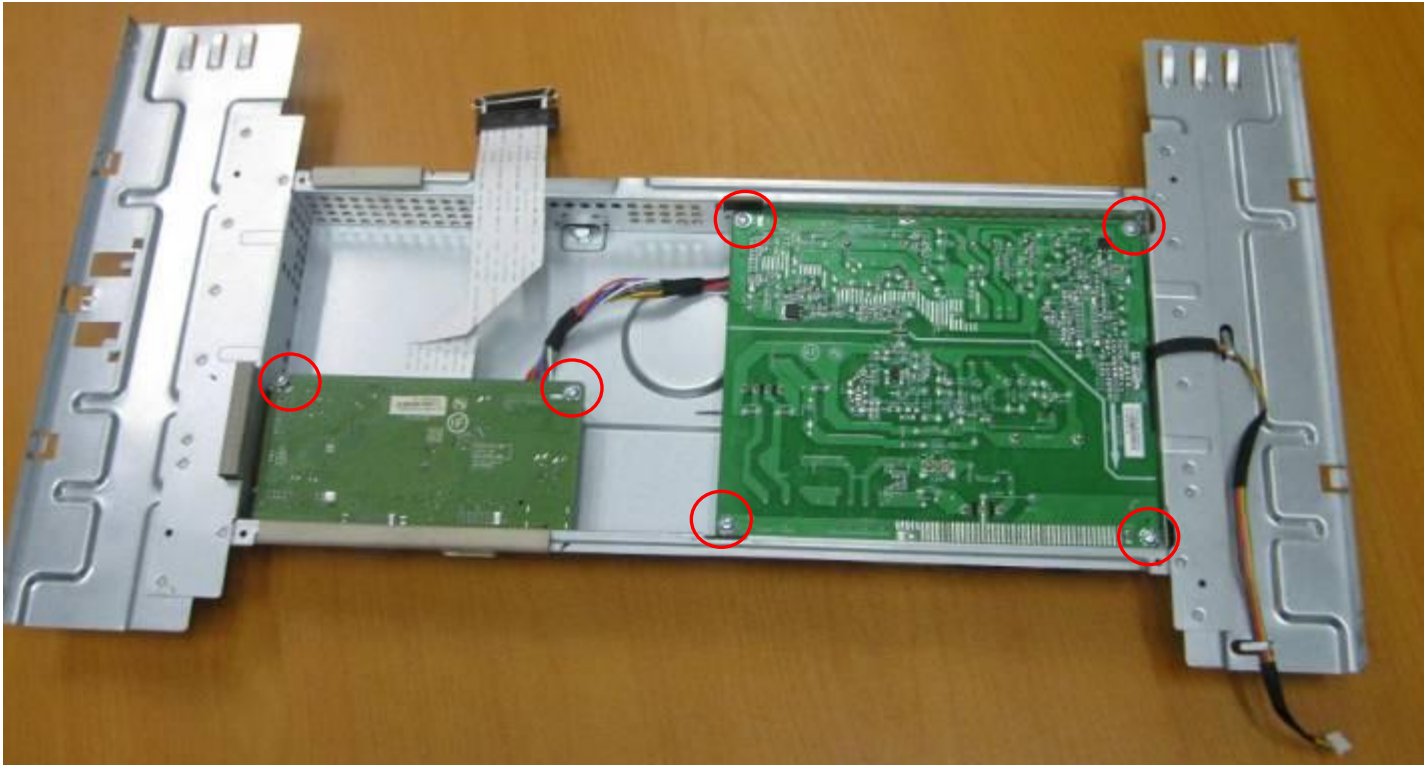
1. Take Screw(x8) Off From P.C.B

2. Take Screw(x1) Off From P.C.B





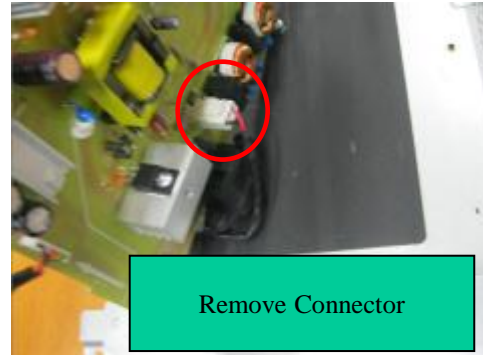
## Take Screw(x6) Off From P.C.B



# Take Off P.C.B From Chassis& Remove BKT (Printed Circuit Assemblies>10cm\*\*2)



USB BOARD



Remove Connector



Interface Board



Interface wire



Power Board



Switch



Panel

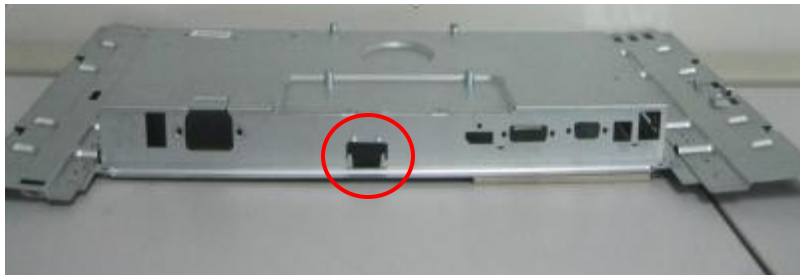
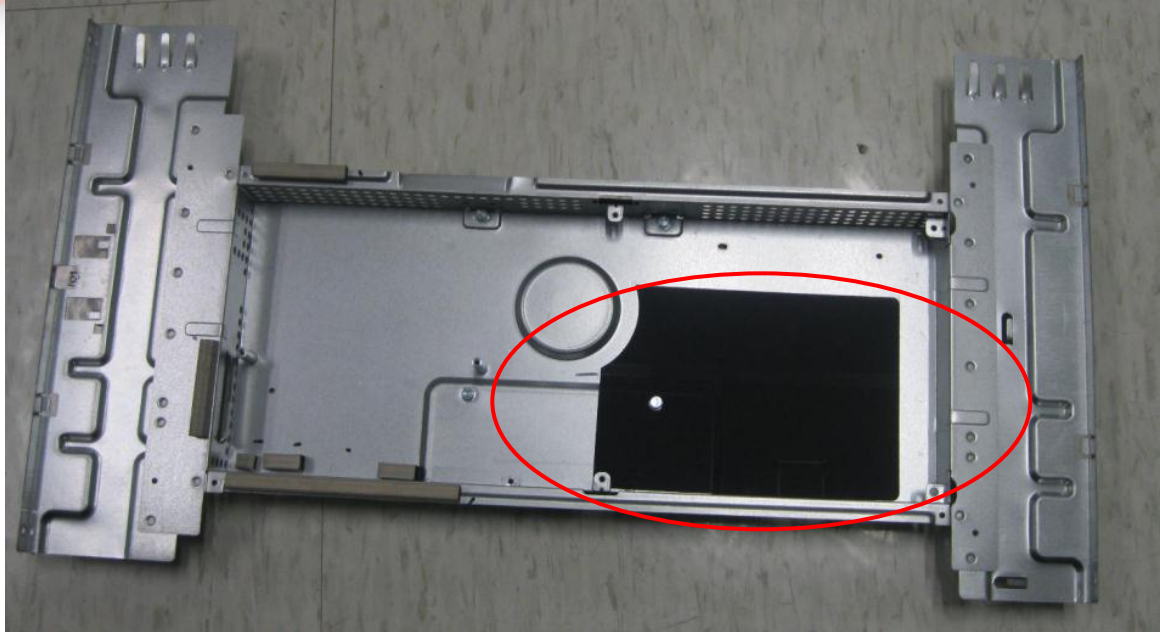


CHASSIS COVER

Dissecting to complete.

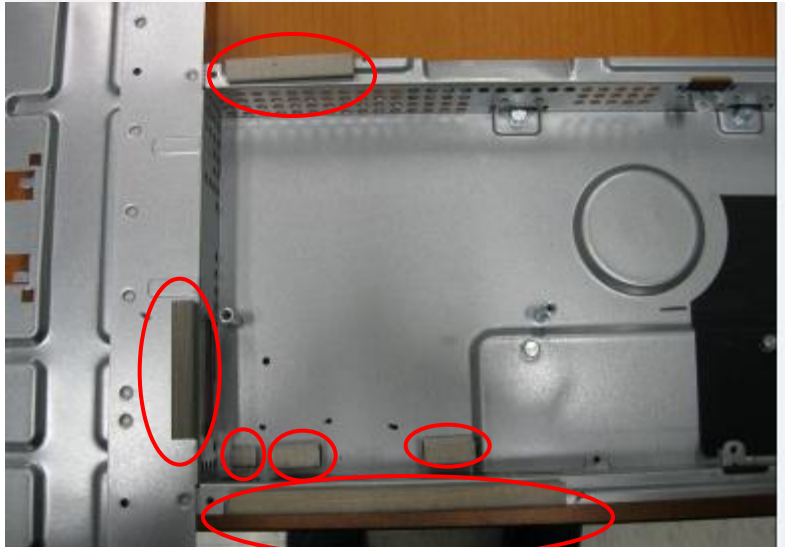


# Remove Mylar From Chassis Cover

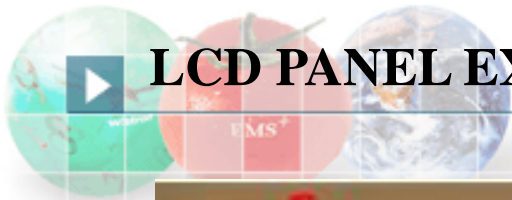




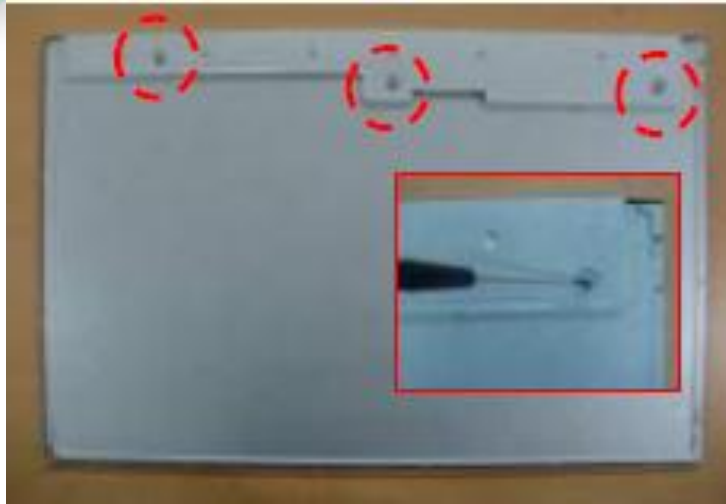
# Remove Gasket From Chassis Cover







# LCD PANEL EXPLODE



1.Loosen C/Shield Screw(\*3),Dismantle C/Shield



2.Dismantle C/Top



3.Separate C/Top ( push the C/Top because of damages on COF)



4.Separate B/Ass'y



# LCD PANEL EXPLODE



5. Loosen B/L Screw (\*5)



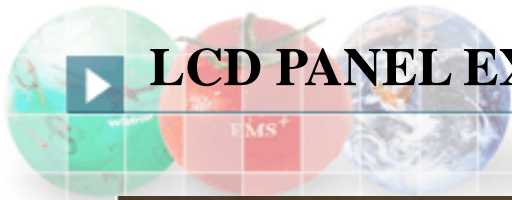
6. Dismantle G/Panel



7. Removal Optical sheets



8. Removal LGP



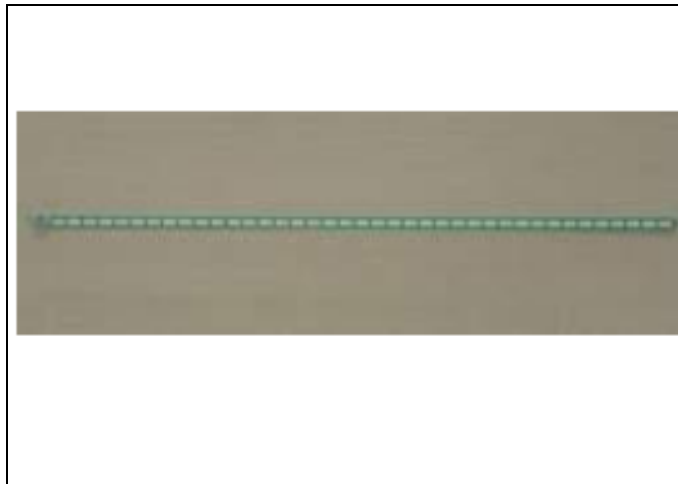
# LCD PANEL EXPLODE



9. Removal Reflector



10. Separate LED Array from C/Bottom Assy



11. LED Array

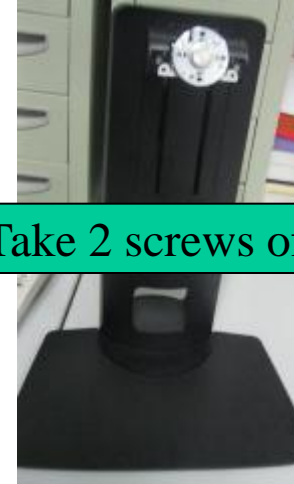
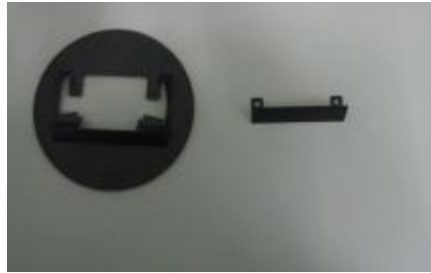
Dissecting to complete.



# Remove VESA Cover, pivot cover off Stand Base



Take 8 screws off

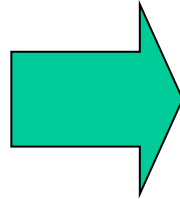


Take 2 screws off





# Remove Riser Lift cover off Stand Base

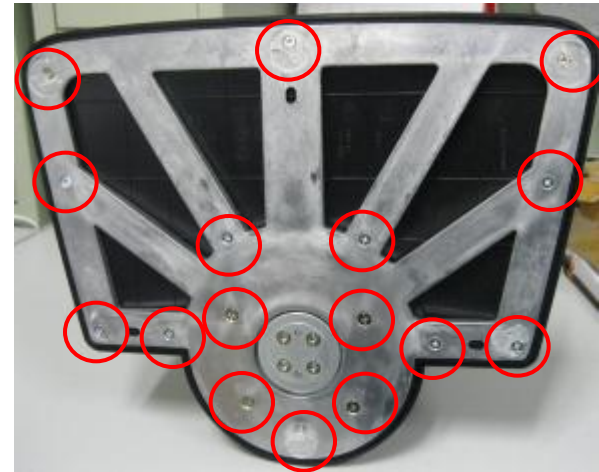
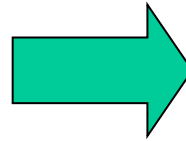




# Remove Base Cover & Base Cover BKT Off Stand Base



Take 6 Rubbers off

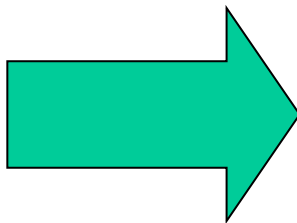


Take 16 Screws off





# Remove Stand Front Cover Off Stand BKT





# Remove Stand Rear Cover Off Stand Base

